# The RF Line NPN Silicon RF Power Transistor

... designed primarily for wideband large–signal driver and predriver amplifier stages in the 200–500 MHz frequency range.

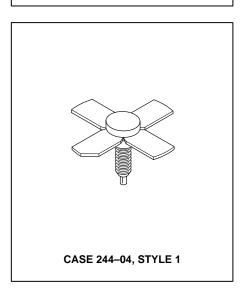
- Guaranteed Performance at 400 MHz, 28 V
   Output Power = 20 Watts
   Power Gain = 10 dB Min
   Efficiency = 50% Min
- 100% Tested for Load Mismatch at all Phase Angles with 30:1 VSWR
- · Gold Metallization System for High Reliability
- Computer-Controlled Wirebonding Gives Consistent Input Impedance

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCEO	33	Vdc
Collector–Base Voltage	VCBO	60	Vdc
Emitter–Base Voltage	VEBO	4.0	Vdc
Collector Current — Continuous — Peak	IC	2.2 3.0	Adc
Total Device Dissipation @ T <sub>C</sub> = 25°C (1) Derate above 25°C	PD	55 310	Watts mW/°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C

# **MRF323**

20 W, 400 MHz RF POWER TRANSISTOR NPN SILICON



### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	3.2	°C/W

## **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			•	•	•
Collector–Emitter Breakdown Voltage (I <sub>C</sub> = 20 mAdc, I <sub>B</sub> = 0)	V(BR)CEO	33	_	_	Vdc
Collector–Emitter Breakdown Voltage (I <sub>C</sub> = 20 mAdc, V <sub>BE</sub> = 0)	V(BR)CES	60	_	_	Vdc
Collector–Base Breakdown Voltage (I <sub>C</sub> = 20 mAdc, I <sub>E</sub> = 0)	V(BR)CBO	60	_	_	Vdc
Emitter-Base Breakdown Voltage (I <sub>E</sub> = 2.0 mAdc, I <sub>C</sub> = 0)	V(BR)EBO	4.0	_	_	Vdc
Collector Cutoff Current (V <sub>CB</sub> = 30 Vdc, I <sub>E</sub> = 0)	ІСВО	_	_	2.0	mAdc
ON CHARACTERISTICS	•			•	•
DC Current Gain (I <sub>C</sub> = 1.0 Adc, V <sub>CE</sub> = 5.0 Vdc)	hFE	20	_	80	_

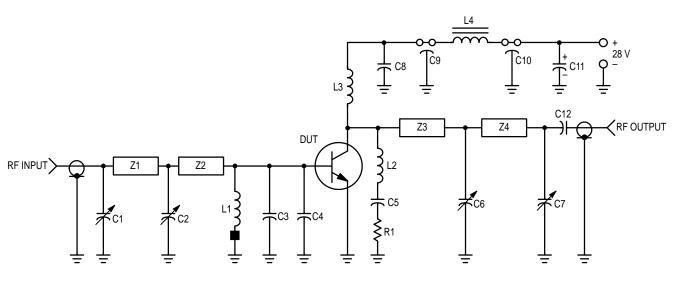
NOTE: (continued)

1. This device is designed for RF operation. The total device dissipation rating applies only when the device is operated as an RF amplifier.



## **ELECTRICAL CHARACTERISTICS** — **continued** ( $T_C = 25$ °C unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
DYNAMIC CHARACTERISTICS	•				
Output Capacitance (V <sub>CB</sub> = 28 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>ob</sub>	_	20	24	pF
FUNCTIONAL TESTS (Figure 1)					
Common–Emitter Amplifier Power Gain (V <sub>CC</sub> = 28 Vdc, P <sub>Out</sub> = 20 W, f = 400 MHz)	GPE	10	11	_	dB
Collector Efficiency (V <sub>CC</sub> = 28 Vdc, P <sub>out</sub> = 20 W, f = 400 MHz)	η	50	60	_	%
Load Mismatch (V <sub>CC</sub> = 28 Vdc, P <sub>out</sub> = 20 W, f = 400 MHz, VSWR = 30:1 all phase angles)	Ψ	No Degradation in Output Power			



C1, C2, C6 — 1.0-20 pF Johanson Trimmer (JMC 5501)

C3, C4 — 47 pF ATC Chip Capacitor C5, C8 — 0.1  $\mu$ F Erie Redcap

C7 — 0.5-10 pF Johanson Trimmer (JMC 5201)

C9, C10 — 680 pF Feedthru

 $C11 - 1.0 \, \mu F 50 \, Volt \, Tantalum$ 

 $C12 - 0.018 \,\mu\text{F}$  Vitramon Chip Capacitor

 $L1 - 0.33 \,\mu\text{H}$  Molded Choke with Ferroxcube Bead (Ferroxcube 56-590-65/4B) on Ground End

L2 — 6 Turns #20 Enamel, 1/4" ID, Closewound

L3 — 4 Turns #20 Enamel, 1/8" ID, Closewound

L4 — Ferroxcube VK200–19/4B

R1 — 5.1  $\Omega$  1/4 Watt

Z1 — Microstrip 0.1" W x 1.35" L

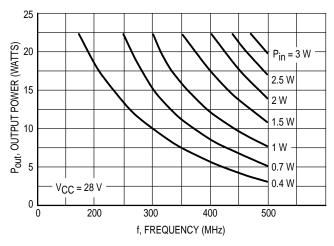
Z2 — Microstrip 0.1" W x 0.55" L

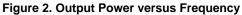
Z3 — Microstrip 0.1" W x 0.8" L Z4 — Microstrip 0.1" W x 1.75" L

Board — Glass Teflon  $\epsilon_{\Gamma}$  = 2.56, t = 0.062"

Input/Output Connectors — Type N

Figure 1. 400 MHz Test Circuit Schematic





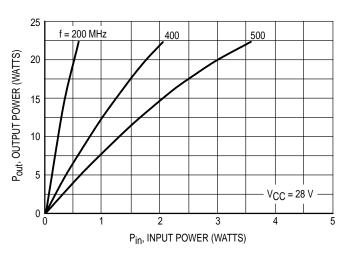


Figure 3. Output Power versus Input Power

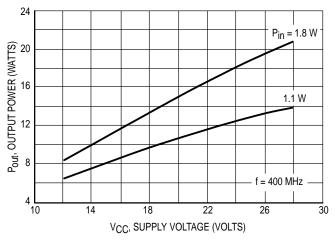


Figure 4. Output Power versus Supply Voltage

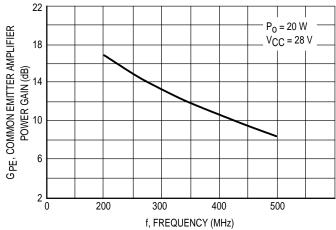
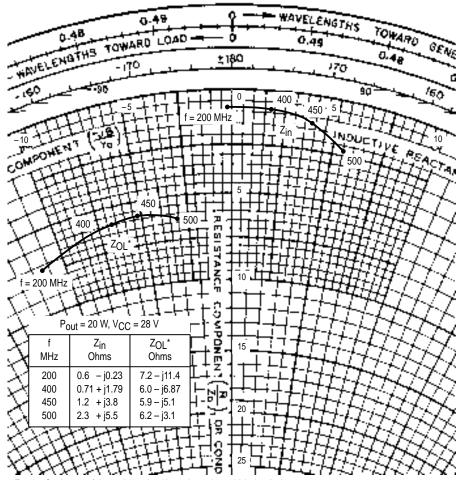


Figure 5. Power Gain versus Frequency

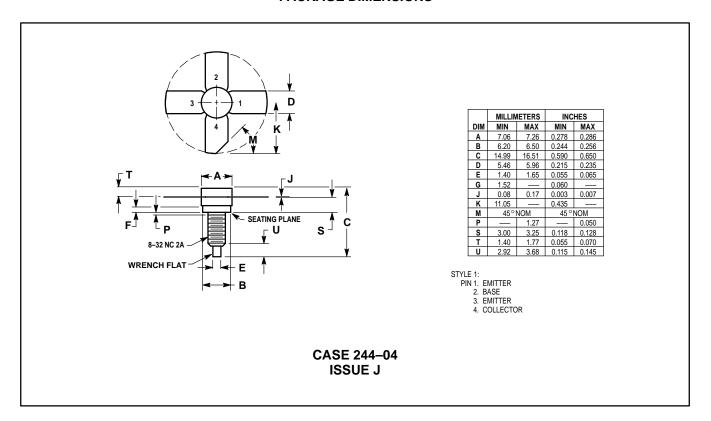
MOTOROLA RF DEVICE DATA MR



Z<sub>OL</sub>\* = Conjugate of the optimum load impedance into which the device output operates at a given output power, voltage and frequency.

Figure 6. Series Equivalent Impedance

## **PACKAGE DIMENSIONS**



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